

Fabrication of a spin injection device having a top-gate structure

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Abstract

A lateral spin injection device having a top-gate structure was fabricated. A clear spin injection from an Fe electrode into an $n\text{-In}_{0.04}\text{Ga}_{0.96}\text{As}$ channel was demonstrated through the observation of spin-valve signals in a cross nonlocal geometry. Furthermore, a gate control of spin-valve signals was achieved. Experiments showed that the amplitude of the spin-valve signal under constant injection current conditions decreased when the channel was depleted by the gate voltage. These results indicate that the developed top-gate structure paves the way to implementing spin transistors.

1. Introduction

Electrical injection of spin-polarized electrons into a semiconductor channel and their control by a gate voltage are major prerequisites for creating viable semiconductor spintronic devices such as spin transistors, which feature nonvolatility, reconfigurable logic functions, and ultralow power consumption [1,2]. While there have been many reports on spin injection into GaAs, Si, or Ge, only a handful of experiments on the gate control of spin signals have been reported [3-5]. Moreover, the gate operation was done only in back-gate structure. However, the back-gate structure suffers from a low operation speed and a large power consumption due to a large parasitic capacitance. Thus, a top-gate structure is indispensable for practical applications. In this study we fabricated a spin injection device having a top-gate structure, and demonstrated a gate control of spin-valve signals in InGaAs channel.

2. Experimental Method

A layer structure consisting of (from the substrate side) a 250-nm-thick undoped GaAs buffer layer, a 700-nm-thick $n\text{-In}_{0.04}\text{Ga}_{0.96}\text{As}$ channel layer, a 15-nm-thick $n\text{-In}_{0.04}\text{Ga}_{0.96}\text{As} \rightarrow n^+\text{-GaAs}$ transition layer, and a 15-nm-thick $n^+\text{-GaAs}$ layer was grown by molecular beam epitaxy (MBE) on semi-insulating GaAs(001) substrates. The doping concentration of the $n\text{-In}_{0.04}\text{Ga}_{0.96}\text{As}$ channel layer was $3 \times 10^{16} \text{ cm}^{-3}$ and that of the $n^+\text{-GaAs}$ layer was $5 \times 10^{18} \text{ cm}^{-3}$ to form a narrow Schottky barrier. Samples were transferred to the second MBE chamber without exposure to air and a 10-nm-thick Fe spin source layer and a 10-nm-thick Al cap layer were then grown at room temperature.

The sample was then processed into a lateral spin transport device by using electron beam lithography and Ar ion milling techniques. The size of the injector contact and detector contact were $0.5 \times 10 \mu\text{m}$ and $1.0 \times 10 \mu\text{m}$, respectively, and the spacing between them was $6.0 \mu\text{m}$. The top-gate electrode of Al was deposited on the $n\text{-In}_{0.04}\text{Ga}_{0.96}\text{As}$ channel between the injector and detector contact (Fig. 1). The size of the top-gate electrode was $2.0 \times 10 \mu\text{m}$. Spin-dependent transport properties for lateral spin transport devices were evaluated in a four-terminal cross-nonlocal geometry where the nonlocal voltage (V_{NL}) between contacts 3 and 1 was measured under a constant current (I_{bias}) supplied between contacts 2 and 4 at 4.2 K (Fig. 1). The negative V_G was applied to the top-gate with respect to terminal 2, which was grounded.

3. Results and Discussion

Figure 2 shows I - V characteristics for (a) a $\text{Fe}/n^+\text{-GaAs}$ Schottky tunnel junction (injector/detector contact) and (b) an $\text{Al}/n\text{-In}_{0.04}\text{Ga}_{0.96}\text{As}$ Schottky junction (gate/channel contact) at 4.2 K. The I - V curves for a $\text{Fe}/n^+\text{-GaAs}$ junction

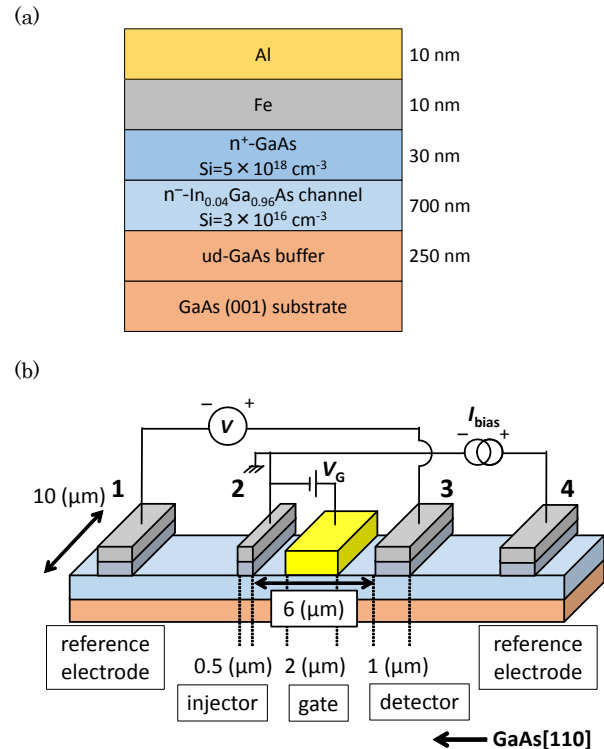


Fig. 1. (a) Layer structure and (b) a lateral spin injection device with a top-gate structure and circuit configuration.

exhibit nonlinear characteristics and are almost symmetric against the bias polarity, indicating that the tunneling conduction is dominant. The typical values of the resistance-area products ($R \cdot A$) was $130 \text{ k}\Omega\mu\text{m}^2$, where R is the resistance which was evaluated from the slope of the I - V curve at $V = 0 \text{ V}$, and A is the junction area. The $R \cdot A$ value was close to our previous results [6]. The I - V curve for an $\text{Al}/\text{n}^- \text{In}_{0.04}\text{Ga}_{0.96}\text{As}$ junction, on the other hand, exhibits a clear rectifying nature, indicating that the Schottky barrier was formed at $\text{Al}/\text{n}^- \text{In}_{0.04}\text{Ga}_{0.96}\text{As}$ interface.

Figure 3 shows the V_G dependence of the channel resistivity (ρ) for V_G from 0 to -1.4 V . The ρ was estimated from the I - V characteristics, in which the voltage between contact-2 and contact-3 was measured while I was supplied

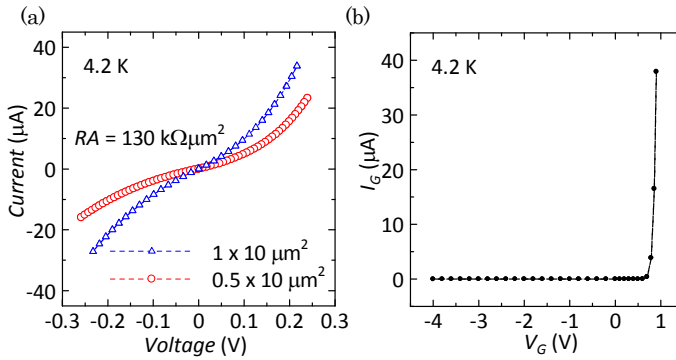


Fig. 2. I - V characteristics for (a) a $\text{Fe}/\text{n}^+ \text{GaAs}$ Schottky tunnel junction (injector/detector contact) and (b) an $\text{Al}/\text{n}^- \text{In}_{0.04}\text{Ga}_{0.96}\text{As}$ Schottky junction.

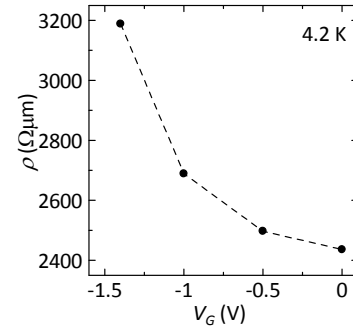


Fig. 3. V_G dependence of the channel resistivity (ρ).

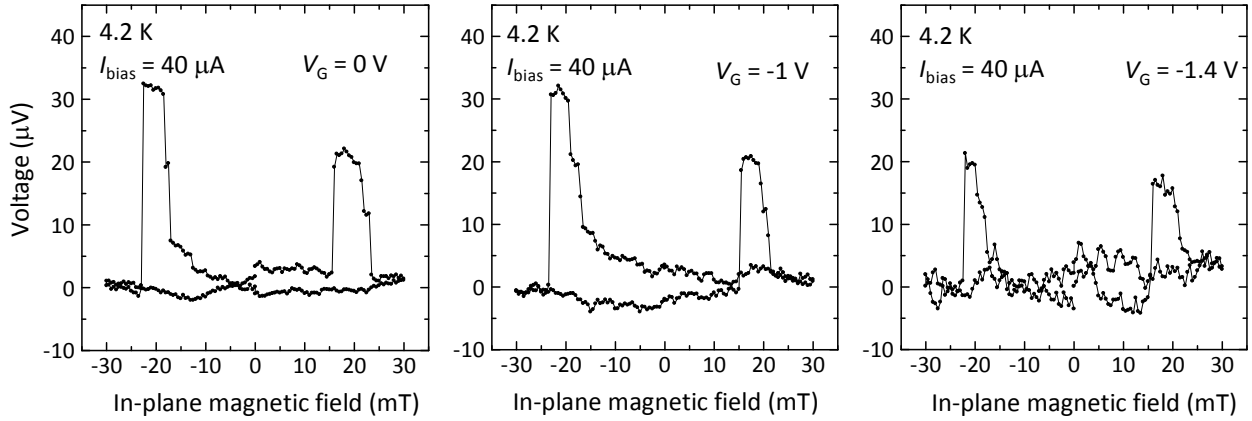


Fig. 4. Spin-valve signals at 4.2 K for a cross nonlocal geometry at $V_G = 0, -1.0$ and -1.4 V .

Acknowledgments

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References

- [1] S. Datta and B. Das, *APL* **56**, 665 (1990).
- [2] S. Sugahara and M. Tanaka, *APL* **84**, 2307 (2004).
- [3] H. Goto et al., *APL* **92**, 212110 (2008).
- [4] T. Sasaki et al., *PRA* **2**, 034005 (2014).
- [5] T. Miyakawa et al., *APEX* **9**, 023103 (2016).
- [6] T. Akiho et al., *APEX* **8**, 093001 (2015).